PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data		
1.1 Company	life.augmented	STMicroelectronics International N.V
1.2 PCN No.		MDG/24/14537
1.3 Title of PCN		ST CALAMBA(Philippines) additional assembly plant for STM32MP13x products in TFBGA 9X9, TFBGA 11X11 and LFBGA 14X14 packages - on listed products.
1.4 Product Category		STM32MP13x products in TFBGA 9X9, TFBGA 11X11 and LFBGA 14X14 packages
1.5 Issue date		2024-06-26

2. PCN Team		
2.1 Contact supplier		
2.1.1 Name	PIKE EMMA	
2.1.2 Phone	+44 1628896111	
2.1.3 Email	emma.pike@st.com	
2.2 Change responsibility		
2.2.1 Product Manager	Ricardo Antonio DE SA EARP	
2.1.2 Marketing Manager	Veronique BARLATIER	
2.1.3 Quality Manager	Pascal NARCHE	

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	

4. Description of change		
	Old	New
4.1 Description	Existing Back-end source: - ASE Kaohsiung Taiwan	Back-end sources: - ASE Kaohsiung Taiwan - ST Calamba Philippines - Additional source For detailed information, please refer to PCN14537 – Additional information attached document.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Additional Assembly site Package darkness changes depending on molding compound. Marking position and size could be different upon assembly site, without any loss of information.	

5. Reason / motivation for change		
	Due to the success on the market of STM32 devices, ST Microcontrollers Division decided to qualify an additional back-end site to maintain state of the art service level to our customers thanks to extra capacity.	
5.2 Customer Benefit	CAPACITY INCREASE	

6. Marking of parts / traceability of change		
·	Change is visible through assembly traceability plant, in the marking: - "AA" for ASE Kaohsiung Taiwan - "78" for ST Calamba Philippines Please refer to PCN 14291– Additional information attached document.	

7. Timing / schedule	
7.1 Date of qualification results	2024-08-30
7.2 Intended start of delivery	2024-09-15
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation		
8.1 Description	14537 MDG-GPM-RER2324 PCN14537 ST CLB add assy plant for STM32MP13x BGA.pdf	

8.2 Qualification report and	Available (see attachment)	Issue	2024-06-26
qualification results	· · ·	Date	

9. Attachments (additional documentations)

14537 Public product.pdf 14537 MDG-GPM-RER2324 PCN14537 ST CLB add assy plant for STM32MP13x BGA.pdf 14537 PCN14537_Additional information.pdf

10. Affected parts			
	10. 1 Current	10.2 New (if applicable)	
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No	
	STM32MP135AAE3		
	STM32MP135AAF3		
	STM32MP135AAG3		
	STM32MP135CAE3		
	STM32MP135CAF3		
	STM32MP135CAG3		
	STM32MP135DAE7		
	STM32MP135DAF7		
	STM32MP135DAG7		
	STM32MP135FAE7		
	STM32MP135FAF7		
	STM32MP135FAG7		

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